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plasma and clean and etch and ("c.sub.3 f.sub.6" or hexafluoropropylene)

0

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JPAB,EPAB	plasma and clean and etch and ("c.sub.3 f.sub.6" or hexafluoropropylene)	0	<u>L5</u>
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USPT	l1 and plasma and clean and etch and ("c.sub.3 f.sub.6" or hexafluoropropylene)	1	<u>L3</u>
USPT	l1 and plasma and clean and etch and "c.sub.3 f.sub.6" (((134/\$)!([CCLS])))	0	<u>L2</u>
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